

EP 7 Core and accessories

 Series/Type:
 B65839, B65840

 Date:
 February 2025

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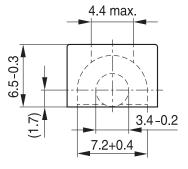
EP 7 Core B65839

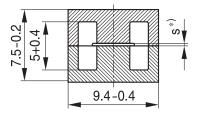
- To IEC 63093-5
- For transformers featuring high inductance and low overall height
- For power applications
- Delivery mode: sets

Magnetic characteristics (per set)

$$\begin{split} \Sigma I/A &= 1.52 \text{ mm}^{-1} \\ I_e &= 15.7 \text{ mm} \\ A_e &= 10.3 \text{ mm}^2 \\ A_{min} &= 8.5 \text{ mm}^2 \\ V_e &= 162 \text{ mm}^3 \end{split}$$

Approx. weight 1.4 g/set





*) gapped (one-sided)

FEP0115-F-E

Material	A _L value	s	μ _e	Ordering code
		approx.		
	nH	mm		
T38	63 ±3%	0.20	76	B65839A0063A038
	100 ±3%	0.13	121	B65839A0100A038
	160 ±5%	0.08	194	B65839A0160J038
	200 ±6%	0.06	243	B65839A0200C038
	250 ±7%	0.05	303	B65839A0250E038
T57	63 ±3%	0.20	76	B65839A0063A057
	100 ±3%	0.13	121	B65839A0100A057
	160 ±5%	0.08	194	B65839A0160J057
	200 ±6%	0.06	243	B65839A0200C057
	250 ±7%	0.05	303	B65839A0250E057
N45	63 ±3%	0.20	76	B65839A0063A045
	100 ±3%	0.13	121	B65839A0100A045
	160 ±5%	0.08	194	B65839A0160J045
	200 ±6%	0.06	243	B65839A0200C045
	250 ±7%	0.05	303	B65839A0250E045
N87	63 ±3%	0.20	76	B65839A0063A087
	100 ±3%	0.12	121	B65839A0100A087
	160 ±5%	0.07	194	B65839A0160J087
	200 ±6%	0.06	243	B65839A0200C087
	250 ±7%	0.05	303	B65839A0250E087

Gapped (A_L values/air gaps examples)



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Ungapped

Material	A _L value	μ _e	P _V	Ordering code
	nH		W/set	
N95	1300 +30/–20%	1580	< 0.08 (200 mT, 100 kHz, 25 °C) < 0.075 (200 mT, 100 kHz, 100 °C)	B65839A0000R095
N45	1500 +30/-20%	1820		B65839A0000R045
N30	2000 +30/-20%	2430		B65839A0000R030
T57	1500 +30/-20%	1820		B65839A0000R057
T65	3000 +30/-20%	3640		B65839A0000R065
T38	5200 +40/-30%	6310		B65839A0000Y038
N87	1100 +30/-20%	1330	< 0.08 (200 mT, 100 kHz, 100 °C)	B65839A0000R087

Other A_L values/air gaps and materials available on request – see Processing remarks on page 7.



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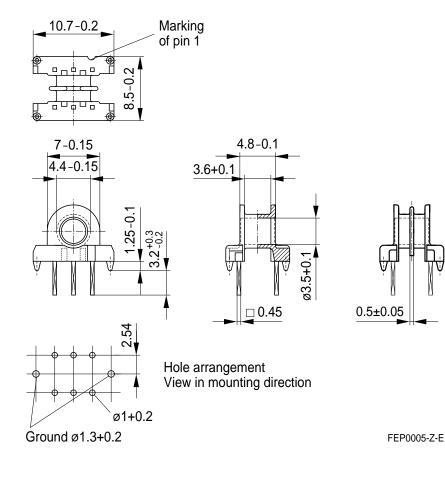
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Coil former

Material:	GFR thermosetting plastic (UL 94 V-0, insulation class to IEC 60085: F $ m \triangleq$ max. operating temperature 155 °C)
	Sumikon PM 9630 [®] [E41429 (M)], color code black,
	SUMITOMO BAKELITE CO LTD
Solderability:	to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s
Resistance to	soldering heat: to IEC 60068-2-20, test Tb, method 1B: 350 °C, 3.5 s
Winding:	see Processing notes, 2.1
Pins:	Squared pins

Coil former					Ordering code
Sections	A _N mm ²	l _N mm	A_R value $\mu\Omega$	Terminals	
1	4.7	17.7	128.7	6	B65840B1006D001
2	4.2	17.7	143.8	6	B65840C1006D002

Coil former



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SMD

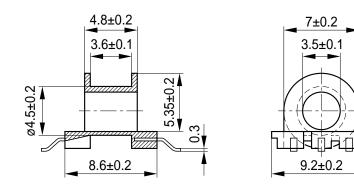
SMD coil former with gullwing terminals

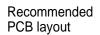
Material: GFR liquid crystal polymer (UL 94 V-0), color code black Sumika Super E4008[®] [E54705 (M)], SUMITOMO CHEMICAL CO LTD

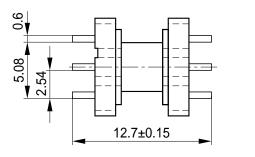
Solderability: to IEC 60068-2-58, test Td, method 6 (Group 3): 245 °C, 3 s

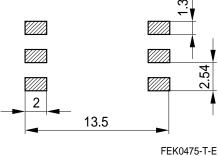
Resistance to soldering heat: to IEC 60068-2-58, test Td, method 6 (Group 3): 255 °C, 10 s permissible soldering temperature for wire-wrap connection on coil former: 400 °C, 1 s

Sections	A _N mm ²	l _N mm	A_R value $\mu\Omega$	Terminals	Ordering code
1	4.5	18.1	138.1	6	B65840N1106T001









Please read *Cautions and warnings* and *Important notes* at the end of this document.

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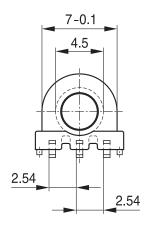
SMD

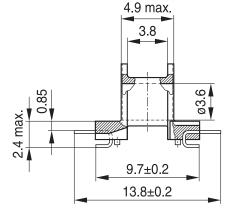
Coil former

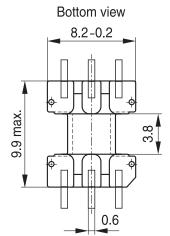
Material: GFR liquid crystal polymer (UL 94 V-0, insulation class to IEC 60085: F = max. operating temperature 155°C), color code black Sumika Super E4008 [E54705 (M)], SUMITOMO CHEMICAL CO LTD Solderability: IEC 60068-2-58, test Td, method 6 (Group 3): 245 °C, 3 s

Resistance to soldering heat: to IEC 60068-2-58, test Td, method 6 (Group 3): 255 °C, 10 s permissible soldering temperature for wire-wrap connection on coil former: 400 °C, 1 s

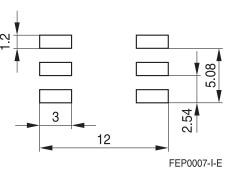
Sections	A _N mm ²	l _N mm	A_R value $\mu\Omega$	Terminals	Ordering code
1	4.7	18	132.9	6	B65840H1106T001







Recommended PCB layout



Please read *Cautions and warnings* and *Important notes* at the end of this document.

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Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter "General - Definitions, 8.1".

Effects of core combination on A_L value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter "General - Definitions, 8.1".

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Ferrite Accessories

Our ferrite accessories have been designed and evaluated only in combination with our ferrite cores. We explicitly point out that our ferrite accessories or our ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

We assume no warranty or reliability for the combination of our ferrite accessories with cores and other accessories from any other manufacturer.

Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter *"Processing notes"*, section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.



Cautions and warnings

Display of ordering codes for TDK Electronics products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications, on the company website or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.tdk-electronics.tdk.com/orderingcodes.

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Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A _e	Effective magnetic cross section	mm ²
AL	Inductance factor; $A_L = L/N^2$	nH
A _{L1}	Minimum inductance at defined high saturation ($\cong \mu_a$)	nH
A _{min}	Minimum core cross section	mm ²
A _N	Winding cross section	mm ²
A _R	Resistance factor; A _R = R _{Cu} /N ²	μΩ = 10 ⁻⁶ Ω
В	RMS value of magnetic flux density	Vs/m², mT
ΔB	Flux density deviation	Vs/m², mT
Ê	Peak value of magnetic flux density	Vs/m², mT
ΔÂ	Peak value of flux density deviation	Vs/m², mT
B _{DC}	DC magnetic flux density	Vs/m², mT
B _R	Remanent flux density	Vs/m², mT
B _S	Saturation magnetization	Vs/m², mT
C ₀	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
E _a	Activation energy	J
f	Frequency	s ⁻¹ , Hz
f _{cutoff}	Cut-off frequency	s ⁻¹ , Hz
f _{max}	Upper frequency limit	s ⁻¹ , Hz
f _{min}	Lower frequency limit	s ⁻¹ , Hz
f _r	Resonance frequency	s ⁻¹ , Hz
f _{Cu}	Copper filling factor	
g	Air gap	mm
H	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H _{DC}	DC field strength	A/m
H _c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ^{–6} cm/A
h/µ _i ²	Relative hysteresis coefficient	10 ^{–6} cm/A
I	RMS value of current	A
I _{DC}	Direct current	A
î	Peak value of current	A
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k ₃	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Symbols and terms

Symbol	Meaning	Unit
ΔL/L	Relative inductance change	Н
L ₀	Inductance of coil without core	Н
L _H	Main inductance	Н
L _p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
Ls	Series inductance	Н
l _e	Effective magnetic path length	mm
I _N	Average length of turn	mm
Ν	Number of turns	
P _{Cu}	Copper (winding) losses	W
P _{trans}	Transferrable power	W
P _V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = $\omega L/R_s$ = 1/tan δ_L)	
R	Resistance	Ω
R _{Cu}	Copper (winding) resistance (f = 0)	Ω
R _h	Hysteresis loss resistance of a core	Ω
ΔR_h	R _h change	Ω
R _i	Internal resistance	Ω
R _p	Parallel loss resistance of a core	Ω
R _s	Series loss resistance of a core	Ω
R _{th}	Thermal resistance	K/W
R _V	Effective loss resistance of a core	Ω
S	Total air gap	mm
Т	Temperature	°C
ΔT	Temperature difference	К
Т _С	Curie temperature	°C
t	Time	S
t _v	Pulse duty factor	
tan δ	Loss factor	
tan δ_L	Loss factor of coil	
tan δ_r	(Residual) loss factor at $H \rightarrow 0$	
tan δ_{e}	Relative loss factor	
tan δ _h	Hysteresis loss factor	
tan δ/μ _i	Relative loss factor of material at $H \rightarrow 0$	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V _e	Effective magnetic volume	mm ³
Z	Complex impedance	Ω
Z _n	Normalized impedance $ Z _n = Z / N^2 \times \varepsilon (I_e / A_e)$	Ω/mm

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Symbols and terms

Symbol	Meaning	Unit			
α	Temperature coefficient (TK)				
α_{F}	Relative temperature coefficient of material	1/K			
α _e	Temperature coefficient of effective permeability	1/K			
٤ _r	Relative permittivity				
Φ	Magnetic flux	Vs			
η	Efficiency of a transformer				
η _B	Hysteresis material constant	mT ⁻¹			
٩i	Hysteresis core constant	A-1H-1/2			
λ _s	Magnetostriction at saturation magnetization				
u	Relative complex permeability				
uo	Magnetic field constant	Vs/Am			
la	Relative amplitude permeability				
[⊥] app	Relative apparent permeability				
ι _e	Relative effective permeability				
ι _i	Relative initial permeability				
ι _p '	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)				
ւթ"	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)				
ι _r	Relative permeability				
[⊥] rev	Relative reversible permeability				
ι _s '	Relative real (inductive) component of $\overline{\mu}$ (for series components)				
ι _s "	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)				
¹ tot	Relative total permeability				
	derived from the static magnetization curve				
)	Resistivity	Ωm^{-1}			
E I/A	Magnetic form factor	mm ⁻¹			
Cu	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	S			
ω	Angular frequency; ω = 2 Π f	s ⁻¹			

All dimensions are given in mm.

Surface-mount device



Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
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